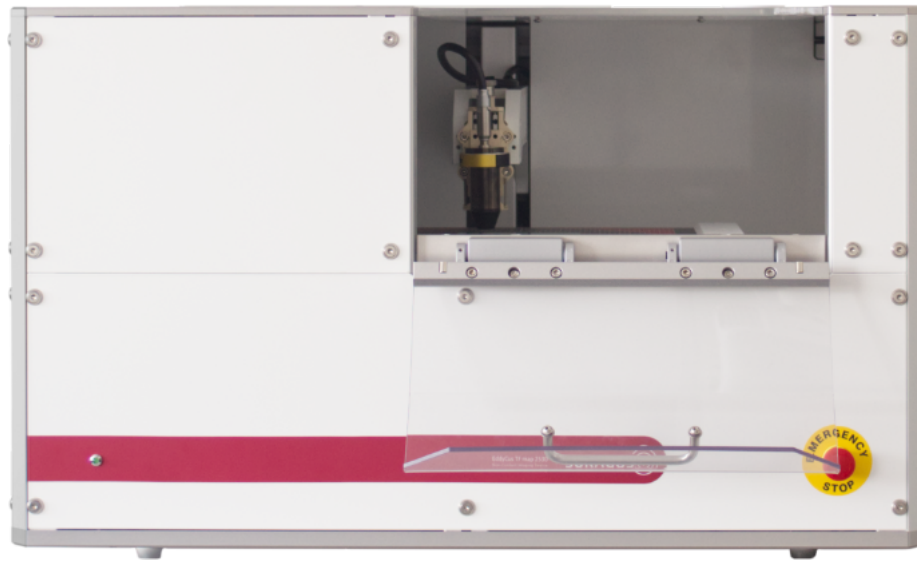


## EddyCus<sup>®</sup> map 2530RMT – Resistivity Imaging Device

P\_2530RMT\_21



### Highlights

- ▶ Contact-free imaging
- ▶ High speed (10,000 points in 5 min)
- ▶ Repeatable and accurate
- ▶ High resolution (9 to 90,000 points)
- ▶ Mapping of encapsulated layers
- ▶ Homogeneity and defect imaging

### Processes

- ▶ Classification and sorting
- ▶ Ingot casting and drawing (FZ, CZ)
- ▶ Implantation and doping
- ▶ Annealing and tempering
- ▶ Composition & structure assessment
- ▶ Melting, sintering, heat treatment
- ▶ EDM processability

### Applications

- ▶ Wafer resistivity imaging
- ▶ Ingot and boule resistivity imaging
- ▶ Sputter target composition imaging
- ▶ Purity assessment
- ▶ Electrical discharge machining
- ▶ Material sorting (map: homogeneity assessment)
- ▶ Melting, casting, sintering
- ▶ Defect imaging and integrity assessment

### Materials


- ▶ Semiconductors
  - ▶ Si (mono, poly)
  - ▶ SiC, SiSiC
  - ▶ GaAs
  - ▶ GaN
- ▶ Alloys
- ▶ Metals
- ▶ Graphite
- ▶ Graphene
- ▶ Compounds
- ▶ Composites

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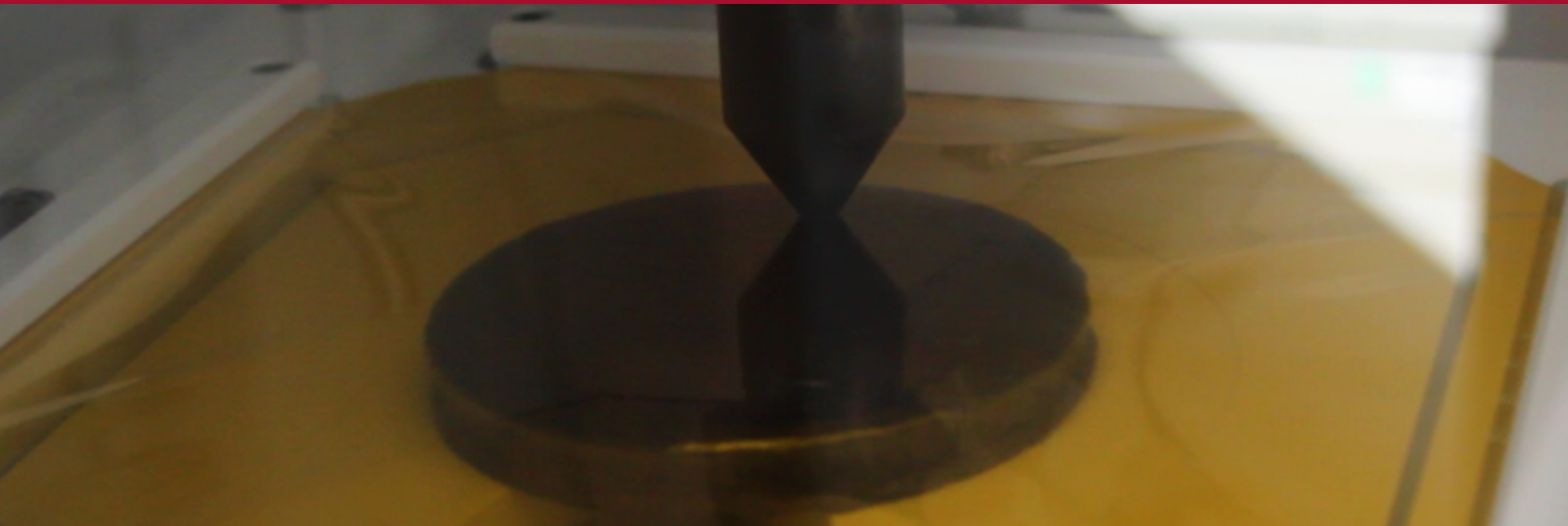
For further questions:  
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Visit us at:  
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[www.suragus.com/EddyCusMap2530](http://www.suragus.com/EddyCusMap2530)

Engineered and Made in Germany 



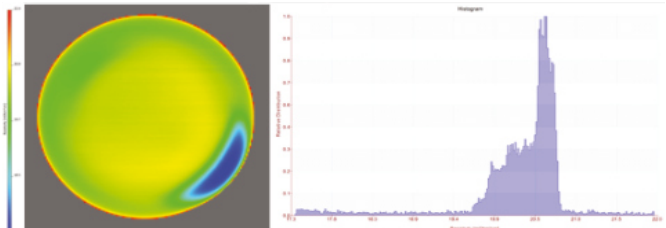


Measurement technology	High frequency eddy current sensor
Substrates	Boules, pucks, wafers
Max. scanning area	8 inch / 205 mm x 205 mm x 100 mm
Edge effect correction / exclusion	2 – 10 mm (depending on size, range, setup and requirements)
Max. sample thickness / sensor gap	100 mm
Resistivity range	0.1 – 100 mOhm·cm (lower and higher on request)
Conductivity range	0.01 – 65 MS/m
Pitch	0.1 – 10 mm
Spot size (coil size)	1 – 9 mm (depending on coil size)
Penetration depth (frequency)	1 – 10 mm (depending on frequency)
Speed	150 mm per second (time 1 to 30 minutes)
Device dimensions (w/h/d) / weight	31.5" x 19.1" x 33.5" / 785 mm x 486 mm x 850 mm / 90 kg
Further available features	Sheet resistance imaging, metal layer thickness imaging, advanced impedance spectroscopy using EddyEVA

Device Control and Software

- ▶ Pre-defined measurement and product recipes (sizes, pitches, thresholds)
- ▶ Line scan, histogram and area analysis
- ▶ Black and colored image coding
- ▶ Csv & pdf export
- ▶ SPC summary and export
- ▶ 3 user levels
- ▶ Material database for parameter conversion
- ▶ Edge effect compensation
- ▶ Storage and import of data
- ▶ Export of data sets (e.g. to EddyEva, MS Excel, Origin)

Boule Resistivity Imaging – Histogram View



Advanced Impedance Spectroscopy by EddyEVA Software

